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WHAT IS CLAIMED IS:

1. A method for manufacturing circuit devices, the method comprising:

forming conductive patterns on a planar body, the
5 conductive patterns forming mounting portions including mounting areas of a circuit element;

disposing the circuit element on the conductive pattern;

performing resin sealing by bringing a lower mold having
air vents into contact with a backface of the planar body and
10 by sealing a surface of the planar body with an insulating resin
so that the circuit element is covered therewith; and

separating each mounting portion.

2. The method for manufacturing circuit devices as set
forth in Claim 1, wherein blocks are formed by a plurality of
15 mounting portions arranged in a matrix form, and resin sealing
is performed by each cavity in each block.

3. The method for manufacturing circuit devices as set
forth in Claim 1, wherein the planar body is a conductive foil,
the conductive foil having a surface provided with conductive
20 patterns formed in a convex shaped by separation grooves,

4. The method for manufacturing circuit devices as set
forth in Claim 1, wherein the planar body is an insulating sheet
having multi-layered conductive patterns laminated via an

insulating layer.

5. The method for manufacturing circuit devices as set forth in Claim 1, wherein the air vents are disposed in parallel.

5 6. The method for manufacturing circuit devices as set forth in Claim 5, wherein the air vent provided at a central part is formed to be larger than the air vent provided at a peripheral part.

7. The method for manufacturing circuit devices as set forth in Claim 1, wherein a remaining part of the planner body around the block is sandwiched by a mold.

8. The method for manufacturing circuit devices as set forth in Claim 1, wherein the circuit element has either one of or both of a semiconductor bare chip and a chip circuit component fixed thereto.

9. The method for manufacturing circuit devices as set forth in Claim 1, wherein a plurality of blocks are aligned, in each block the conductive patterns forming a plurality of mounting portions are arranged in a matrix form on the planner body.

10. The method for manufacturing circuit devices as set forth in Claim 9, wherein the insulating resin is formed by simultaneously subjecting all of the blocks of the conductive

foil to transfer molding.

11. The method for manufacturing circuit devices as set forth in Claim 1, wherein the air vent strides over a peripheral part of the cavity and is extended from inside the cavity to
5 an outer part of the cavity.